

## **AMENDMENTS TO THE CLAIMS**

The following listing of claims will replace all prior versions and listings of claims in the application.

### **LISTING OF CLAIMS**

1. – 4. (Cancelled)

5. (Currently Amended) A device for forming a wiring, comprising:

a liquid drop ejecting device for ejecting liquid drops onto a substrate by scanning

on the substrate in at least first and second scanning movements; and

a surface-treatment device for surface-treating the substrate[[,]]; and

a drying unit for removing a dispersion medium contained in the liquid drop;

wherein the device for forming a wiring ejects the liquid drops on the substrate such that a predetermined regular interval is disposed between each pair of ejected liquid drops in the first scanning movement, the predetermined regular interval being twice a diameter of the previously-ejected liquid drop or less,

the liquid drops ejected in the second scanning movement are disposed to fill the predetermined regular intervals,

the substrate is surface-treated by the surface-treatment device so that a contact angle of the ejected liquid drops with respect to the substrate is in a predetermined range, and

a volume of the liquid drops ejected in the first scanning movement is equal to a volume of the liquid drops ejected in the second scanning movement.

6. (Previously Presented) A device for forming wiring according a wiring according to Claim 5, wherein the contact angle is in a range of 15° to 45°.

7. – 15. (Cancelled)

16. (Previously Presented) A device for forming wiring according to Claim 5, wherein the predetermined regular intervals are determined by controlling: a relative speed of the liquid drop ejecting device with respect to the substrate; and a frequency of the ejection by the liquid drop ejecting device.